

**In the Specification:**

Please delete the abstract and add the following abstract:

-- A method and associated structure for forming a conductive path within a laminate. A conductive element is pressed into an opening in the laminate such that a portion of at least one end of the conductive element extends beyond a surface of the laminate. A compressive pressure is applied to the portion of the at least one end of the conductive element. The compressive pressure applied to the at least one end of the conductive element forms a contact pad extending beyond the surface of the laminate. The conductive element may include an inner element covered by an outer element.--